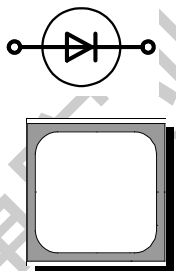


Type	Ag* Al*	V _{DRM} / V _{RRM}	I _{F(AV)} [A]	Chip Size [mm] x [mm]	Package Options
DWP 75	<input checked="" type="checkbox"/> <input checked="" type="checkbox"/>	1600	115	8.70 8.70	sawn on foil <input checked="" type="checkbox"/> unsawn wafer <input checked="" type="checkbox"/> * in waffle pack <input checked="" type="checkbox"/>

*Frontside options

*Please contact IXYS chip sales



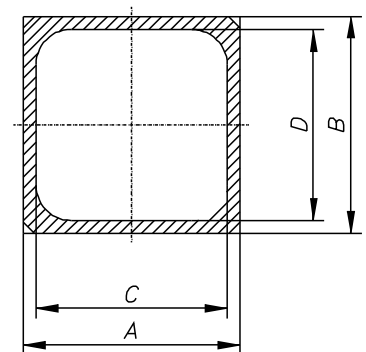
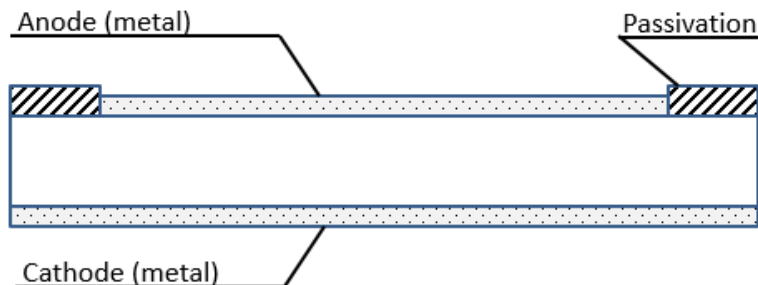
Mechanical Parameters

Area active	53.98 mm ²	<p>Features</p> <ul style="list-style-type: none"> • planar technology • anode top • glassivation • soft recovery rectifier diode <p>Applications</p> <ul style="list-style-type: none"> • DC Power Supplies • Field Supply for DC motors • Battery DC Power Supplies • Power Rectifiers
Area total	75.69 mm ²	
Wafer size Ø	150 mm	
Thickness	265 µm	
Material	Si	
Max. possible chips per wafer	177	
Passivation front side	Glassivation	
Metallization top side	solderable: Al / Ti / Ni / Ag *	
top side	bondable: Al	
Metallization backside	solderable (only): Al / Ti / Ni / Ag *	
Recom. wire bonds (Al)	Number 6	
	Ø 500 µm	
Reject Ink Dot Size	Ø 0.4-1.0 mm	
Recom. Storage Environment		
sawn on foil	in org. container, in dry nitrogen < 6 month	
unsawn wafer	in org. container, in dry nitrogen < 2 year	
in waffle pack	in org. container, in dry nitrogen < 2 year	
T	-40 ... 40 °C	

*Sinterable top/bottom side on request

Dimensions

A	B	C	D
[mm]	[mm]	[mm]	[mm]
8.70	8.70	7.3	7.3



Electrical parameters

Symbol	Conditions	Ratings		
		min.	typ.	max.
V_D / V_R	$T_{VJ} = 25^\circ\text{C}$	1600		V
I_R	$V_R = V_{RRM}$ $T_{VJ} = 25^\circ\text{C}$			100 μA
	$V_R = 0.8 \cdot V_{RRM}$ $T_{VJ} = 150^\circ\text{C}$			2 mA
V_F	$I_F = 200 \text{ A}$ $T_{VJ} = 25^\circ\text{C}$			1.26 V
	$T_{VJ} = 125^\circ\text{C}$			1.22 V
V_{FO}	For power-loss calculations only			0.86 V
r_F	$T_{VJ} = 150^\circ\text{C}$			1.8 m Ω
T_{VJ}		-40		150 $^\circ\text{C}$
$I_{F(AV)}$ *	$T_C = 100^\circ\text{C}$ 180° rect. $T_{VJ} = 150^\circ\text{C}$		115	A
I_{FSM} *	$T_{VJ} = 45^\circ\text{C}$ t = 10 ms (50) Hz, sine			1400 A
	$V_R = 0 \text{ V}$ t = 8.3 ms (60) Hz, sine			1520 A
	$T_{VJ} = 150^\circ\text{C}$ t = 10 ms (50) Hz, sine			tbd A
	$V_R = 0 \text{ V}$ t = 8.3 ms (60) Hz, sine			tbd A
$I^2 t$ *	$T_{VJ} = 45^\circ\text{C}$ t = 10 ms (50) Hz, sine			9800 A s ²
	$V_R = 0 \text{ V}$ t = 8.3 ms (60) Hz, sine			9630 A s
	$T_{VJ} = 150^\circ\text{C}$ t = 10 ms (50) Hz, sine			tbd A s ²
	$V_R = 0 \text{ V}$ t = 8.3 ms (60) Hz, sine			tbd A s ²
R_{thJC} *	DC current			0.33 K/W

* Data according to assembled Chip

bondable version

Data according to IEC 60747

Terms of Conditions and Usage

The data contained in this product data sheet is exclusively intended for technically trained staff. The user will have to evaluate the suitability of the product for the intended application and the completeness of the product data with respect to his application. The specifications of our components may not be considered as an assurance of component characteristics. Should you require product information in excess of the data given in this product data sheet or which concerns the specific application of our product, please contact the sales office, which is responsible for you. Due to technical requirements our product may contain dangerous substances. For any information on the types in question please contact the sales office/partner, which is responsible for you.

Should you intend to use the product in aviation applications, in health or life endangering or life support applications, please notify. For any such applications we urgently recommend

- to perform joint risk and quality assessments;

- the conclusion of quality agreements;

- to establish joint measures to ensure application specific product capabilities and notify that IXYS may delivery dependent on the realization of any such measures.